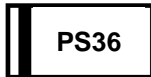


RoHS Compliant Product  
A suffix of "-C" specifies halogen-free

## FEATURES

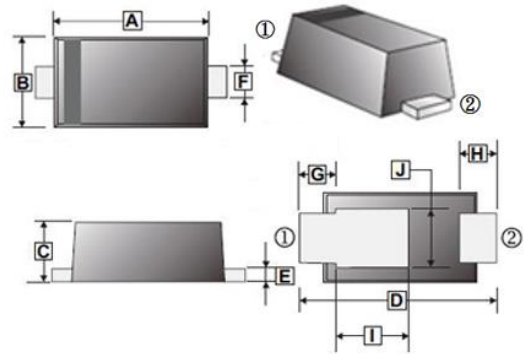
- Heatsink Structure
- Low Profile, Typical Thickness 0.8mm
- Moisture Sensitivity: Level 1, Per J-STD-020
- High Temperature Soldering Guaranteed: 260°C/10s

## MARKING



↑  
Cathode

## SOD-123DT



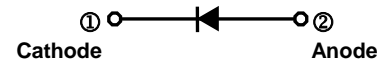
REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.90	3.10	F	0.85	1.05
B	1.90	2.10	G	0.60 REF.	
C	0.75	0.90	H	0.40	0.85
D	3.50	3.90	I	1.66 REF.	
E	0.10	0.25	J	1.30	1.70

## PACKAGE INFORMATION

Package	MPQ	Leader Size
SOD-123DT	3K	7 inch

## ORDER INFORMATION

Part Number	Type
SM360DT-C	Lead (Pb)-free and Halogen-free



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	Rating		Unit	
		Typ.	Max.		
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	60		V	
Maximum RMS Voltage	V <sub>RMS</sub>	42			
Maximum DC Blocking Voltage	V <sub>DC</sub>	60			
Maximum Average Forward Rectified Current	I <sub>F</sub>	3		A	
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rate Load	I <sub>FSM</sub>	100		A	
Rating for Fusing (t<8.3ms)	I <sup>2</sup> t	41.7		A <sup>2</sup> S	
Instantaneous Forward Voltage @ I <sub>F</sub> =3A	V <sub>F</sub>	T <sub>A</sub> =25°C	0.61	0.65	V
		T <sub>A</sub> =125°C	0.52	0.6	
Instantaneous Reverse Current @ Rated DC Blocking Voltage	I <sub>R</sub>	T <sub>A</sub> =25°C	4.1	50	uA
		T <sub>A</sub> =125°C	3.8	10	mA
Typical Junction Capacitance <sup>3</sup>	C <sub>J</sub>	160		pF	
Typical Thermal Resistance from Junction-Ambient <sup>1</sup>	R <sub>θJA</sub>	60		°C/W	
Typical Thermal Resistance from Junction-Case <sup>2</sup>	R <sub>θJC</sub>	28			
Typical Thermal Resistance from Junction-Lead <sup>1</sup>	R <sub>θJL</sub>	6			
Operating Junction & Storage Temperature	T <sub>J</sub> , T <sub>STG</sub>	-55~150		°C	

Notes:

1. The thermal resistance from junction to ambient or lead, mounted on P.C.B with 5x5mm copper pads, 2oz, FR4 PCB.
2. The thermal resistance from junction to case, mounted on P.C.B with recommended copper pads, 2oz, FR4 PCB.
3. Measured at 1MHz and applied reverse voltage of 4V D.C.

**CHARACTERISTIC CURVES**

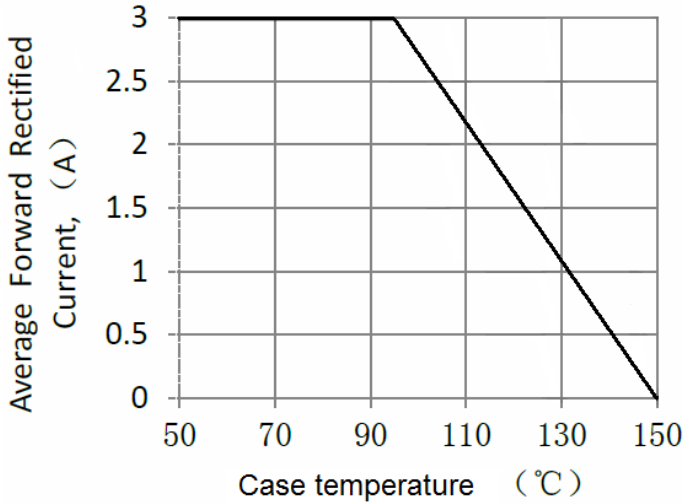


Figure 1. Forward Current Derating Curve

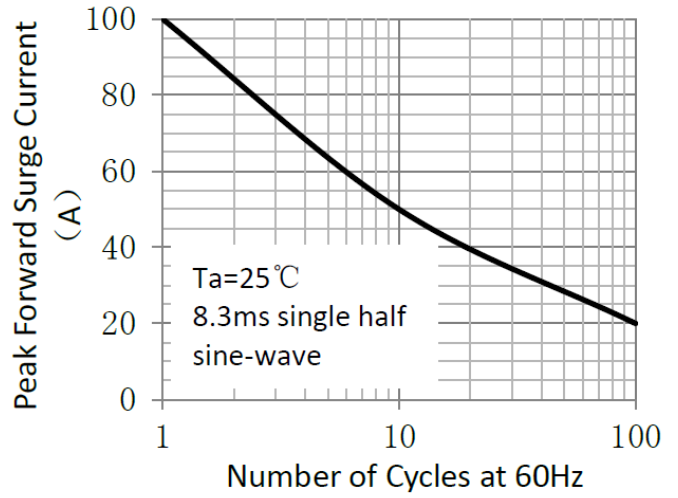


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

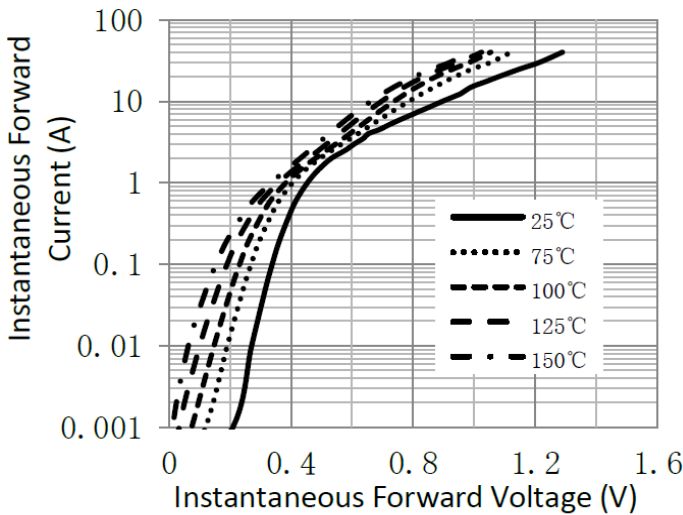


Figure 3. Typical Instantaneous Forward Characteristics

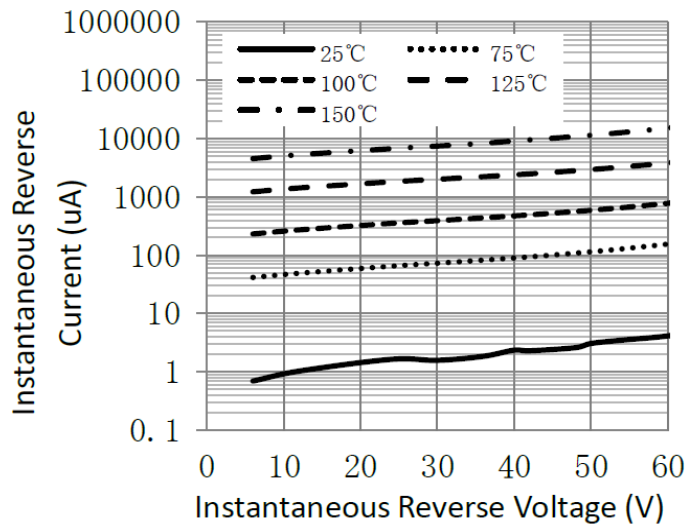


Figure 4. Typical Reverse Characteristics

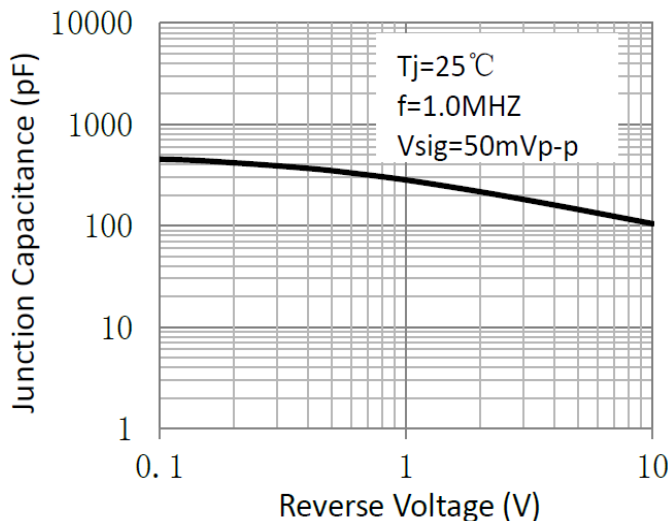
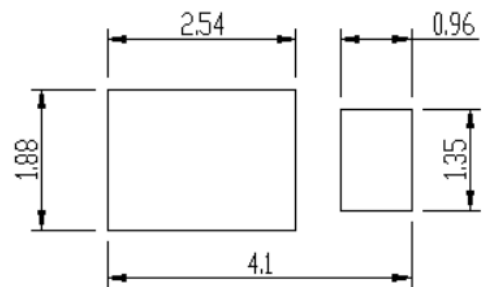


Figure 5. Typical Junction Capacitance



\*Dimensions in millimeters

Figure 6. Mounting Pad Layout